**E160-3U-1**

Circuit Pattern:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

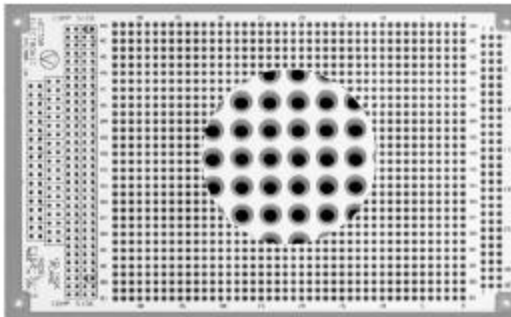
Pad-Per-Hole
 6.30"/.062"
 3.94"
 35
 FR4 Epoxy Glass
 T44, T46, T49, T68
 R32
 CCK160-3U
 RE96MWR
 (Available Separately)
 .042"

- 0.100" grid
- Voltage and ground buses around board perimeter, both sides
- Isolated solder pad around each hole, both sides
- Pad and bus surfaces solder-coated for user convenience
- For solder, Wire-Wrap or mixed wiring methods
- Layout paper and instructions included
- Row and column legends provided
- Plated-thru holes

E160-3U-2**3Ux160mm**

Pad-Per-Hole

- Power & GND planes both sides

**E160-3U-3**

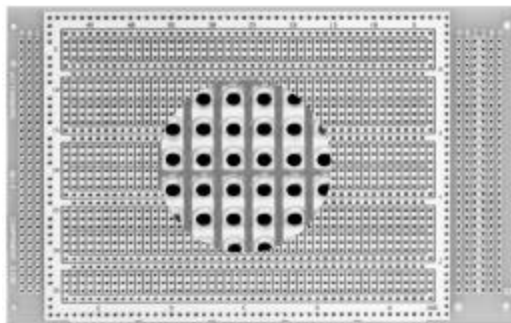
Circuit Pattern:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

Voltage Ground Plane
 Both sides
 6.30"/.062"
 3.94"
 45
 FR4 Epoxy Glass
 T44, T46, T49, T68
 R50, R51, R52, R53
 CCK160-3U
 RE96MWR
 (Available Separately)
 .055"

- 0.100" grid
- Overall voltage and ground planes on opposite board sides provide excellent shielding and power distribution
- Plane surfaces solder coated
- To simulate plated-thru holes committed to voltage or ground planes, use Vector T123 eyelets, available separately (for use without pins)
- Layout paper and instructions included
- Row and column legends provided

**4614**

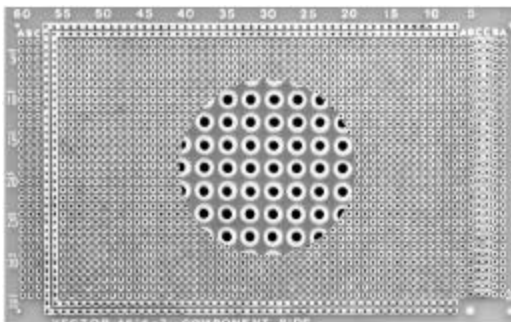
Circuit Pattern:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

3-Hole Solder Pad
 6.30"/.062"
 3.94"
 20
 FR4 Epoxy Glass
 T44, T46, T49, T68
 R32
 CCK160-3U
 RE96MWR
 (Available Separately)
 .042"

- 0.100" grid
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Interleaved buses on both sides, back-to-back
- Pad and bus surfaces solder-coated for user convenience
- Layout paper and instructions included
- Row and column legends provided
- Plated-thru holes

**4614-3**

Circuit Pattern:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

Pad-Per-Hole
 6.30"/.062"
 3.94"
 30
 FR4 Epoxy Glass
 T44, T46, T49, T68
 R32
 CCK160-3U
 RE96MWR
 (Available Separately)
 .042"

- 0.100" grid
- Voltage and ground buses around board perimeter, both sides
- Pad and bus surfaces solder-coated for user convenience
- For solder, Wire-Wrap or mixed wiring methods
- Layout paper and instructions included
- Row and column legends provided
- Plated-thru holes